



Material Content Data Sheet



Sales Product Name		BSL305SPE H6327		Issued		20. July 2018		
MA#		MA001241632						
Package		PG-TSOP6-6-6		Weight*		13.61 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.007	0.05		517	
	noble metal	gold	7440-57-5	0.027	0.20		2003	
	inorganic material	silicon	7440-21-3	0.416	3.06	3.31	30558	33078
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		87	
	non noble metal	titanium	7440-32-6	0.006	0.04		434	
	non noble metal	chromium	7440-47-3	0.018	0.13		1302	
	non noble metal	copper	7440-50-8	5.882	43.22	43.40	432177	434000
wire	non noble metal	copper	7440-50-8	0.078	0.57	0.57	5714	5714
encapsulation	organic material	carbon black	1333-86-4	0.067	0.49		4923	
	plastics	epoxy resin	-	1.441	10.58		105843	
	inorganic material	silicondioxide	60676-86-0	5.193	38.15	49.22	381527	492293
leadfinish	non noble metal	tin	7440-31-5	0.299	2.20	2.20	21962	21962
plating	noble metal	silver	7440-22-4	0.176	1.30	1.30	12953	12953
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com